



APPLICATION DATA SHEET

Electronic Version v14

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Title of Invention	CHIP-PACKAGING WITH BONDING OPTIONS HAVING A PLURALITY OF PACKAGE SUBSTRATES	
Application Type : regular, utility Attorney Docket Number : FTCP0036USA		
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 as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.		